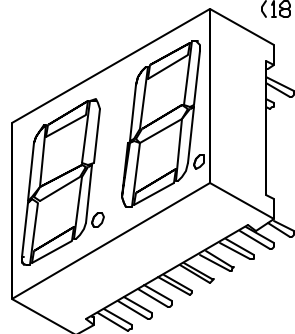
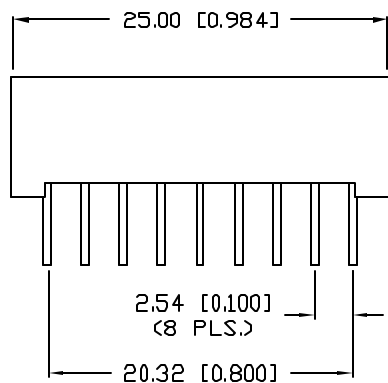
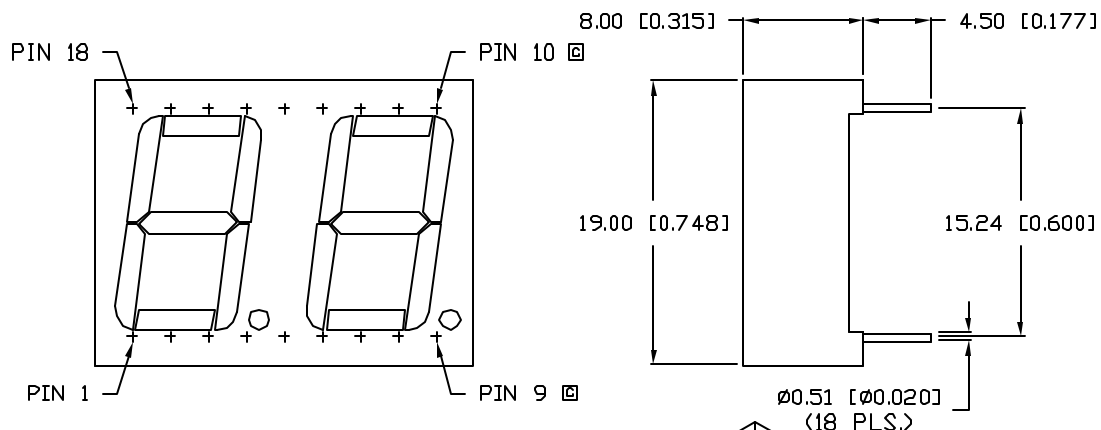
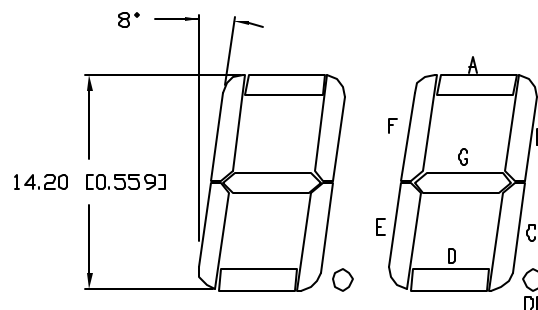


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CHARACTER DETAIL



DIG.1

DIG.2

PART NUMBER		REV.
LDD-A514R1		D
REV.	E.C.N. NUMBER AND REVISION COMMENTS	DATE
A	E.C.N. #10188. & 10113.	6.24.96
B	E.C.N. #10BRDR.	2.12.99
C	E.C.N. #10732. & REDRAWN IN 3D.	5.2.01
D	E.C.N. #11148.	4.26.07

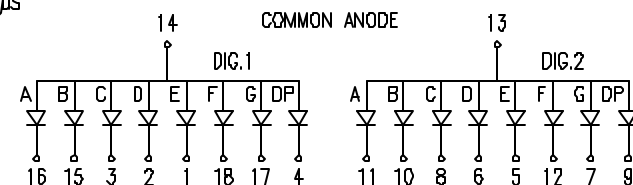
ELECTRO-OPTICAL CHARACTERISTICS  $T_A=25^\circ\text{C}$   $I_f=10\text{mA}$

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		635		nm	
FORWARD VOLTAGE		2.0	2.5	$V_f$	
REVERSE VOLTAGE	5.0			$V_r$	$I_r=100\mu\text{A}$
AXIAL INTENSITY		3900		$\mu\text{cd}$	$I_f=10\text{mA}$
EMITTED COLOR:	RED				
FACE COLOR:	GRAY				
SEGMENT COLOR:	MILKY WHITE DIFFUSED				

LIMITS OF SAFE OPERATION AT  $25^\circ\text{C}$  PER CHIP

PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	150	mA
STEADY CURRENT	30	mA
POWER DISSIPATION	105	mW
DERATE FROM $25^\circ\text{C}$	-1.2	mW/ $^\circ\text{C}$
OPERATING, STORAGE TEMP.	-40 TO +85	$^\circ\text{C}$
SOLDERING TEMP.	+260	$^\circ\text{C}$
2.0mm FROM BODY		3 SEC. MAX

\*  $t < 10\mu\text{s}$



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\*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), X.X=±0.5 (±0.020), X.XX=±0.25 (±0.010), X.XXX=±0.127 (±0.005). LEAD SIZE=±0.05 (±0.002), LEAD LENGTH=±0.75 (±0.030), MIN=+0.00 DECIMAL PRECISION MAX.=+0.00 DECIMAL PRECISION

REV.	PART NUMBER
D	LDD-A514R1

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0.56" SEVEN SEGMENT, DUAL DIGIT DISPLAY,  
 635nm RED CHIPS, GRAY FACE WITH WHITE SEGMENTS,  
 COMMON ANODE, RIGHT DECIMAL PLACE.

**RELIABILITY NOTE**  
 OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY:	CHECKED BY:	APPROVED BY:	DATE:
JC			8.9.94
			PAGE: 1 OF 1
			SCALE: N/A